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PATENT & TRADEMARK OFFICE PATENT APPLICATION

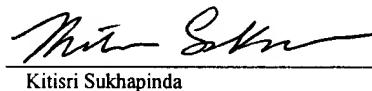
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group)
Art Unit: 2827)
Attorney)
Docket No.: TKA0029)
Applicant: Hiroshi Kimura)
Invention: SEMICONDUCTOR DEVICE, ITS
MANUFACTURING METHOD AND ELECTRODEPOSITION
FRAME)
Serial No: 09/837,022)
Filed: April 18, 2001)
Examiner: Mitchell, James M.)

Certificate Under 37 CFR 1.8(a)

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D.C. 20231

on August 20, 2002



Kitisri Sukhapinda

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RESPONSE TO OFFICE ACTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated May, 23, 2002 in connection with the
above-identified application, please amend the application as follows:

IN THE CLAIMS

Please cancel claims 2 and 3, and substitute claims 1 and 5 with the following:

1. (Amended) A semiconductor device comprising:
a semiconductor element bonded on a first metallic layer;
a wire for electrically connecting an electrode pad of the semiconductor element to a
second metallic layer; and
a resin package for sealing said semiconductor element,
wherein rear surfaces of the first metallic layer and the second metallic layer are flush
with a bottom of said resin package, and wherein said first metallic layer is thicker than said

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